31/07/03

20030044625

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

162162

(43) International Publication Date
15 August 2002 (15.08.2002)

PCT

(10) International Publication Number
WO 02/062202 A3

(51) International Patent Classification[7]: H01L 21/302, B44C 1/22

(21) International Application Number: PCT/US02/03206

(22) International Filing Date: 5 February 2002 (05.02.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/266,431 5 February 2001 (05.02.2001) US

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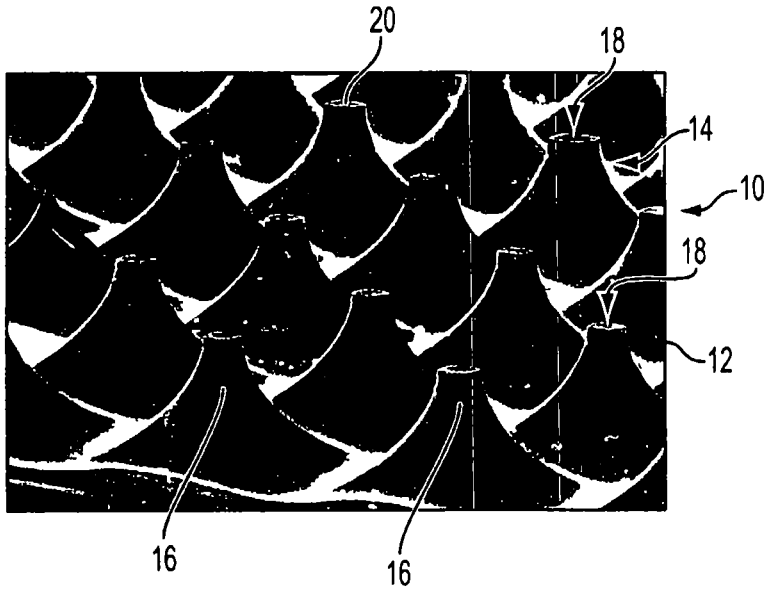
(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

[Continued on next page]

(54) Title: MICROPROTRUSION ARRAY AND METHODS OF MAKING A MICROPROTRUSION



(57) Abstract: A microprotrusion array is formed from a silicon wafer by a plurality of sequential plasma and wet isotropic and anisotropic etching steps. The resulting microprotrusions (14) have sharpened tips (18) or cutting edges formed by wet isotropic etching, wherein each microprotrusion has a substantially pyramid shape with each side (16) having a concave surface. The tip of each microprotrusion has a substantially flat top surface (20) extending parallel to base (12).

WO 02/062202 A3

ACTION

— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
10 October 2002

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.